

**Amendments to the Claims:**

Please amend claims 17 and 32 as follows:

1-16. (Cancelled)

17. (Currently Amended) A test socket for receiving a microfeature device having a substrate and a plurality of interconnect elements projecting from the substrate, the test socket comprising a recess having a lead-in surface and a support surface, the support surface including a plurality of open apertures positioned to receive corresponding interconnect elements of the microfeature device, wherein the individual open apertures extend through the test socket and have a cross-sectional dimension less than a cross-sectional dimension of the interconnect elements so that the substrate is spaced apart from the support surface when the microfeature device is received in the recess, and wherein at least a section of the support surface positioned to contact at least one of the interconnect elements is dielectric.

18. (Original) The test socket of claim 17 wherein the apertures in the support surface are arranged in rows and columns corresponding to an array of interconnect elements on the microfeature device.

19. (Original) The test socket of claim 17 wherein:  
the support surface further comprises an opening; and  
the apertures in the support surface are arranged around the perimeter of the opening so that when the microfeature device is received in the recess, the apertures receive the corresponding interconnect elements and the other interconnect elements are positioned at the opening.

20. (Original) The test socket of claim 17 wherein:  
the support surface further comprises an opening; and  
the apertures comprise at least three apertures around the opening.

21. (Original) The test socket of claim 17 wherein the cross-sectional dimension of the individual apertures is from approximately 70 percent to approximately 80 percent of the cross-sectional dimension of the corresponding interconnect elements.

22. (Original) The test socket of claim 17, further comprising:  
a body having the recess and a shelf; and  
a ball support member carried by the shelf and having the support surface.

23. (Original) The test socket of claim 17 wherein the individual apertures comprise a beveled portion.

24. (Previously presented) A test socket for receiving a microfeature device having a substrate and a plurality of interconnect elements projecting from the substrate, the test socket comprising a recess having a lead-in surface and a support surface, the support surface including a plurality of apertures positioned to receive corresponding interconnect elements of the microfeature device, wherein the individual apertures extend through the test socket and have a cross-sectional dimension less than a cross-sectional dimension of the interconnect elements so that the substrate is spaced apart from the support surface when the microfeature device is received in the recess, wherein the test socket further comprises an exterior surface opposite the support surface, and wherein the individual apertures comprise a first beveled portion proximate to the support surface and a second beveled portion proximate to the exterior surface.

25. (Original) The test socket of claim 17 wherein:  
the cross-sectional dimension of the individual apertures is a first, smallest diameter in the apertures; and  
the individual apertures comprise a first portion having the first, smallest diameter and a second portion having a second diameter greater than the first diameter.

26. (Previously presented) A test socket for receiving a microfeature device having a substrate and a plurality of interconnect elements projecting from the substrate, the test socket

comprising a support surface and a plurality of open apertures in the support surface configured to receive corresponding interconnect elements of the microfeature device, wherein individual open apertures extend through the test socket and are configured to receive only a distal portion of a corresponding interconnect element so that the substrate is spaced apart from the support surface when the microfeature device is received in the test socket, and wherein at least a section of the support surface positioned to contact at least one of the interconnect elements is dielectric.

27. (Original) The test socket of claim 26 wherein the individual apertures have a cross-sectional dimension less than a cross-sectional dimension of the corresponding interconnect element.

28. (Original) The test socket of claim 26 wherein the individual apertures comprise a first portion having a first cross-sectional dimension and a second portion having a second cross-sectional dimension greater than the first cross-sectional dimension.

29. (Original) The test socket of claim 26 wherein the apertures in the support surface are arranged in rows and columns corresponding to an array of interconnect elements on the microfeature device.

30. (Original) The test socket of claim 26 wherein:  
the support surface further comprises an opening; and  
the apertures in the support surface are arranged around the perimeter of the opening so that when the microfeature device is received in the test socket, the apertures receive the corresponding interconnect elements and the other interconnect elements are positioned at the opening.

31. (Original) The test socket of claim 26, further comprising:  
a body having a recess to receive the microfeature device and a shelf in the recess; and  
a support member carried by the shelf and having the support surface.

32. (Previously presented) A test socket for receiving a microfeature device having a substrate and a plurality of solder balls on the substrate, the test socket comprising:  
a body including a recess, a lead-in surface partially defining the recess, and a shelf in the recess; and  
a ball support member carried by the shelf, the ball support member including a plurality of open apertures positioned to receive corresponding solder balls of the microfeature device, wherein individual open apertures extend through the ball support member and are sized to receive a portion of a corresponding solder ball so that the substrate is spaced apart from the support surface when the microfeature device is received in the test socket.

33. (Original) The test socket of claim 32 wherein the individual apertures have a diameter less than a diameter of the corresponding solder ball.

34. (Original) The test socket of claim 32 wherein the individual apertures comprise a first portion having a first diameter and a second portion having a second diameter greater than the first diameter.

35. (Original) The test socket of claim 32 wherein the apertures in the ball support member are arranged in rows and columns corresponding to an array of solder balls on the microfeature device.

36. (Original) The test socket of claim 32 wherein:  
the ball support member further comprises an opening; and  
the apertures in the ball support member are arranged around the perimeter of the opening so that when the microfeature device is received in the test socket, the apertures receive the corresponding solder balls and the other solder balls are positioned at the opening.

37. (Currently Amended) A test socket for receiving a microfeature device having a substrate and an array of conductive balls on the substrate, the test socket comprising a support surface and a plurality of open apertures arranged in an array corresponding to the array of conductive balls of the microfeature device, wherein the individual open apertures extend through the test socket and have a first diameter at the support surface and a second diameter spaced apart from the support surface, wherein the second diameter is less than the first diameter such that the substrate is spaced apart from the support surface when the microfeature device is received in the test socket, and wherein at least one of the first and second diameters is less than a diameter of the conductive balls, and wherein at least a section of the support surface positioned to contact at least one of the interconnect elements is dielectric.

38-63. (Cancelled)